

FEATURES AND SPECIFICATIONS

Features and Benefits

- Conforms to EIA/SFF specifications to ensure intermateability with conforming parts
- Gold flash over Palladium Nickel plating for a high durability/reliability interface
- Dual-stack, single-piece design provides space savings with one-step PCB processing
- Optional cover to protect from contact damage during handling
- Available with or without screwlock hardware (71433-0002)
- One-piece enhanced face shield for improved EMI/RFI performance and simple ground termination process

Reference Information

Product Specification: PS-71425-9999
 Packaging: Tray
 UL File No.: E29179
 CSA File No.: LR19980-5
 Mates With: Ultra+ VHDCI plug kit 71425
 Designed In: Millimeters

Electrical

Voltage: 30V
 Current: 0.5A
 Contact Resistance: 50mΩ max.
 Dielectric Withstanding Voltage: 250V AC
 Insulation Resistance: 500 MΩ min.

Mechanical

Mating Force: 0.49N (0.11 lb)
 Unmating Force: 0.15N (0.03 lb)
 Durability: 500 cycles

Physical

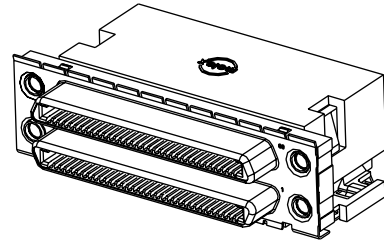
Housing: Black, high-temperature thermoplastic, UL 94V-0
 Contact: Phosphor Bronze
 Plating: Gold flash over Palladium Nickel
 PCB Thickness: 1.57 and 2.36mm (.062 and .093")
 Operating Temperature: -55 to +85°C



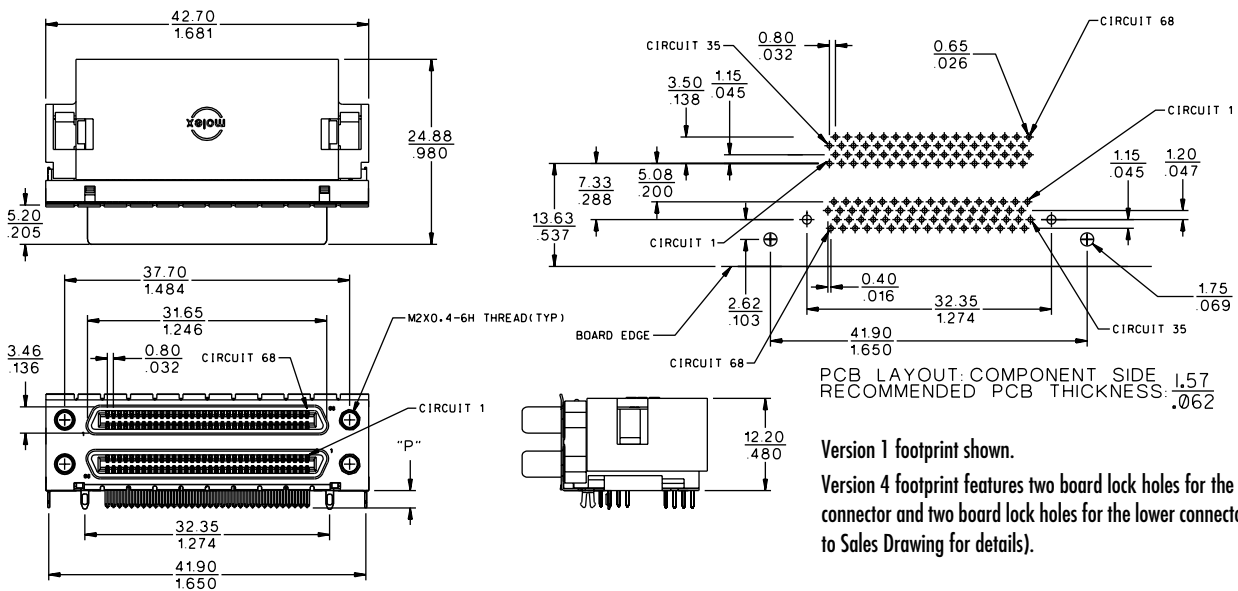
0.80mm (.031") Pitch Ultra+™ VHDCI Wire-to-Board Receptacle

74337

Stacked, Right Angle



CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

| Circuits | Order No. | | | | Footprint Version | Dimension P |
|----------|-----------------|-------------|---------------------------|-----------------------------|-------------------|-------------|
| | With Screwlocks | With Cover | With Screwlocks and Cover | Without Screwlocks or Cover | | |
| 136 | 74337-0040 | 74337-0012 | 74337-0038 | 74337-0016 | 1 | 2.08 (.082) |
| | 74337-0064 | 74337-0051* | 74337-0054 | 74337-0061 | 4 | 2.08 (.082) |
| | 74337-0039 | 74337-0011 | 74337-0037 | 74337-0015 | 1 | 2.30 (.090) |
| | 74337-0073 | 74337-0070 | 74337-0072 | 74337-0071 | 1 | 3.44 (.135) |

* Without enhanced shield and ground tabs

Americas Headquarters

Lisle, Illinois 60532 U.S.A.
 Tel: 1-800-78MOLEX
 Fax: 630-969-1352

Far East North Headquarters

Yamato, Kanagawa, Japan
 Tel: 81-462-65-2324
 Fax: 81-462-65-2366

Far East South Headquarters

Jurong, Singapore
 Tel: 65-6-268-6868
 Fax: 65-6-265-2985

European Headquarters

Munich, Germany
 Tel: 49-89-413092-0
 Fax: 49-89-401527

Corporate Headquarters

2222 Wellington Ct.
 Lisle, IL 60532 U.S.A.
 Tel: 630-969-4550

Visit our Web site at <http://www.molex.com/product/vhdc.html>

molex® **0.80mm (.031") Pitch**
Ultra+™ VHDCI
Wire-to-Board
Dual Stack Receptacle

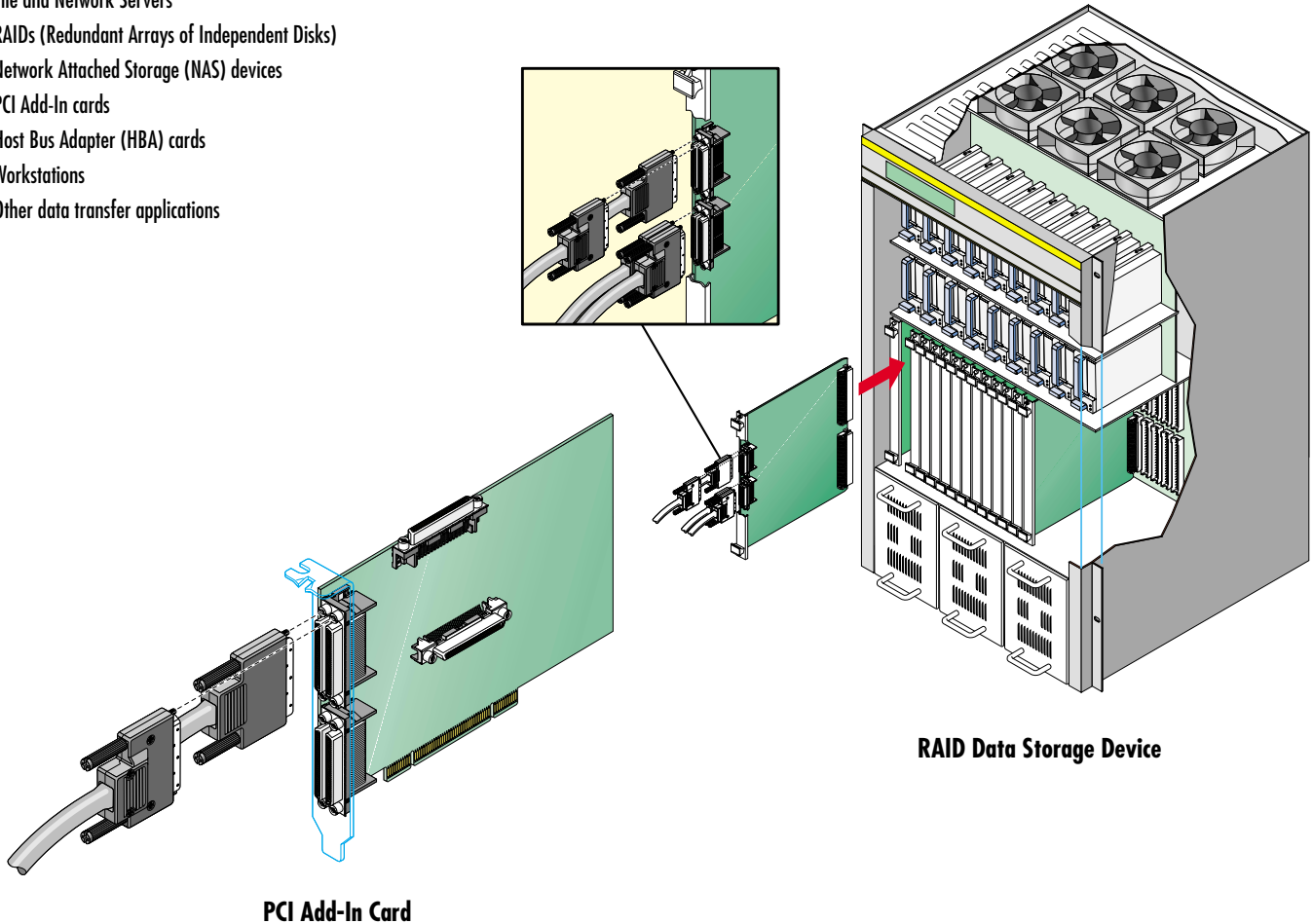
The new 0.80mm (.031") Pitch Dual Stack Ultra+ VHDCI (Very High Density Cable Interface) connectors from Molex are ideal for demanding next generation SCSI applications. They have been designed to meet ANSI/SFF-8441 and SPI-4 requirements while supporting HBA applications and other equipment requiring high port densities.

These space-saving dual-stacked receptacles have 136 circuits in a two-row configuration, providing the most features for maximum performance and reliability. An optional cover is available, eliminating risk of electrical shorts to panels or adjacent printed circuit boards in densely packaged equipment. Panel grounding tabs provide a superior ground path to a panel or bracket for maximum EMI protection. High performance terminals with lead-ins that have a large radius minimize stubbing while improving plug insertion.



APPLICATIONS

- File and Network Servers
- RAIDs (Redundant Arrays of Independent Disks)
- Network Attached Storage (NAS) devices
- PCI Add-In cards
- Host Bus Adapter (HBA) cards
- Workstations
- Other data transfer applications



PCI Add-In Card

RAID Data Storage Device